

FDD8780/FDU8780 N-Channel PowerTrench[®] MOSFET 25V, 35A, 8.5m Ω



General Description

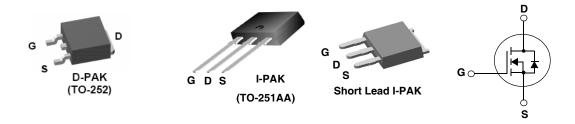
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(on)}$ and fast switching speed.

Application

- Vcore DC-DC for Desktop Computers and Servers
- VRM for Intermediate Bus Architecture

Features

- Max $r_{DS(on)} = 8.5 m\Omega$ at $V_{GS} = 10 V$, $I_D = 35 A$
- Max $r_{DS(on)}$ = 12.0m Ω at V_{GS} = 4.5V, I_D = 35A
- Low gate charge: $Q_{g(10)} = 21nC(Typ)$, $V_{GS} = 10V$
- Low gate resistance
- Avalanche rated and 100% tested
- RoHS Compliant



MOSFET Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DS}	Drain to Source Voltage		25	V
V_{GS}	Gate to Source Voltage		±20	V
	Drain Current -Continuous (Package Limited)		35	
I_D	-Continuous (Die Limited)		60	Α
	-Pulsed	(Note 1)	224	
E _{AS}	Single Pulse Avalanche Energy (Note 2)		73	mJ
P_D	Power Dissipation		50	W
T _J , T _{STG}	Operating and Storage Temperature		-55 to 175	°C

Thermal Characteristics

R_{\thetaJC}	Thermal Resistance, Junction to Case TO-252,TO-251	3.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient TO-252,TO-251	100	°C/W
R _{e,IA}	Thermal Resistance, Junction to Ambient TO-252,1in ² copper pad area	52	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8780	FDD8780	TO-252AA	13"	12mm	2500 units
FDU8780	FDU8780	TO-251AA	N/A(Tube)	N/A	75 units
FDU8780	FDU8780_F071	TO-251AA	N/A(Tube)	N/A	75 units

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	rest Conditions	IVIII	тур	IVIAX	Units	
Off Characteristics							
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$	25			V	
$\frac{\Delta B_{VDSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		12		mV/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20V, V _{GS} = 0V			1 250	μА	
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20V			±100	nA	

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.2	1.8	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25°C		-6.3		mV/°C
	Drain to Source On Resistance	V _{GS} = 10V, I _D = 35A		6.5	8.5	
r		$V_{GS} = 4.5V, I_D = 35A$		9.1	12.0	mΩ
r _{DS(on)}		$V_{GS} = 10V, I_D = 35A$ $T_J = 175^{\circ}C$		10.4	15.0	11122

Dynamic Characteristics

C _{iss}	Input Capacitance	101/1/	1080	1440	pF
Coss	Output Capacitance	─V _{DS} = 13V, V _{GS} = 0V, —f = 1MHz	265	355	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11/11/12	180	270	pF
R_g	Gate Resistance	f = 1MHz	0.9		Ω

Switching Characteristics

t _{d(on)}	Turn-On Delay Time		7	14	ns
t _r	Rise Time	V_{DD} = 13V, I_{D} = 35A V_{GS} = 10V, R_{GS} = 17 Ω	9	18	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10V, R_{GS} = 1722$	43	69	ns
t _f	Fall Time		24	38	ns
Qg	Total Gate Charge	V _{GS} = 0V to 10V	21	29	nC
Qg	Total Gate Charge	$V_{GS} = 0V \text{ to } 5V$ $V_{DD} = 13V$ $I_{D} = 35A$	11.2	16	nC
Q _{gs}	Gate to Source Gate Charge	$I_D = 35A$ $I_C = 1.0 \text{mA}$	3.5		nC
Q_{gd}	Gate to Drain "Miller" Charge	.g	4.7		nC

Drain-Source Diode Characteristics

V		V _{GS} = 0V, I _S = 35A	0.92	1.25	V
v _{SD}	Source to Drain Diode 1 of ward Voltage	V _{GS} = 0V, I _S = 15A	0.84	1.0	·
t _{rr}	Reverse Recovery Time	I _F = 35A, di/dt = 100A/μs	28	42	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 35A$, di/dt = $100A/\mu s$	20	30	nC

Notes:
1: Pulse time < 300μs, Duty cycle = 2%.
2: Starting T_J = 25°C, L = 0.3mH, I_{AS} = 22A ,V_{DD} = 23V, V_{GS} = 10V.



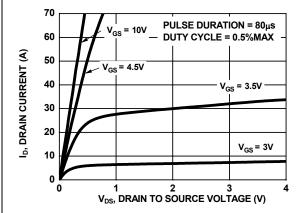
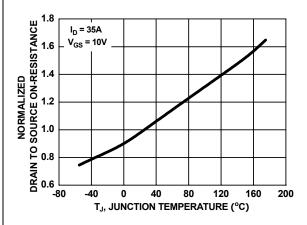


Figure 1. On Region Characteristics

Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage



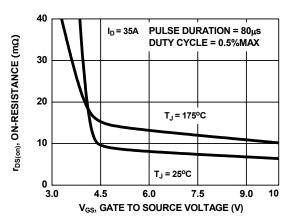
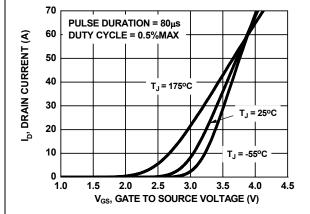


Figure 3. Normalized On Resistance vs Junction Temperature

Figure 4. On-Resistance vs Gate to Source Voltage



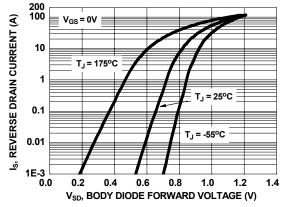
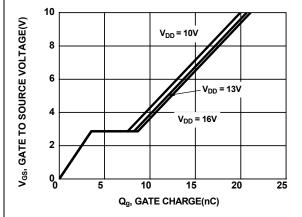


Figure 5. Transfer Characteristics

Figure 6. Source to Drain Diode Forward Voltage vs Source Current





4000

(Lg)
1000

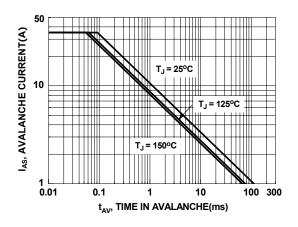
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Figure 7. Gate Charge Characteristics

Figure 8. Capacitance vs Drain to Source Voltage



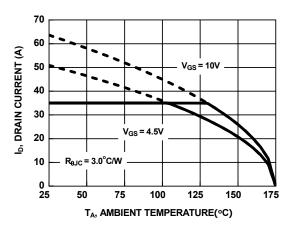
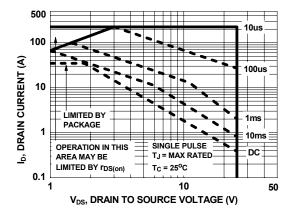


Figure 9. Unclamped Inductive Switching Capability

Figure 10. Maximum Continuous Drain Current vs Case Temperature



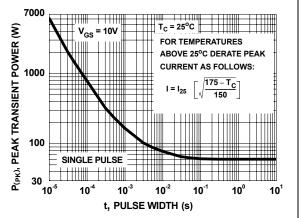


Figure 11. Forward Bias Safe Operating Area

Figure 12. Single Pulse Maximum Power Dissipation



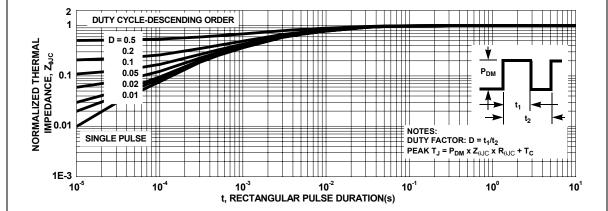


Figure 13. Transient Thermal Response Curve

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